

SiC SCHOTTKY DIODE TYPE 12A

Features

- Low conduction and switching loss
- Zero reverse recovery
- High surge current capability
- Positive temperature coefficient device
- RoHS compliant and halogen free
- Temperature independent switching behavior
- Suitable for high power application
- V_{DC} 650 V
- I_F ($T_C=135/155^\circ\text{C}$) 18A/12A

Benefits

- Increase parallel device convenience
- Enable high temperature application
- Realize compact and lightweight systems
- Allow high frequency operation
- Higher system efficiency
- High reliability

Applications

- Switching mode power supply
- PFC
- UPS
- Motor drives
- Flywheel diode in power inverters
- Solar/Wind renewable energy

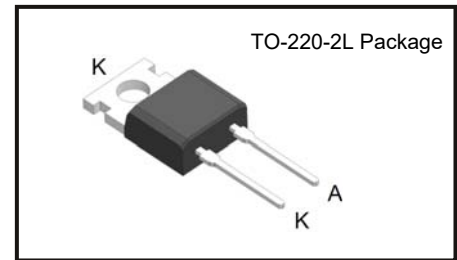
Maximum Ratings

Operating Junction Temperature : -55°C to $+175^\circ\text{C}$

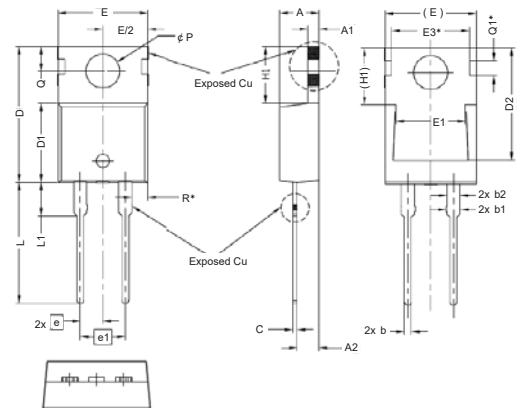
Storage Temperature : -55°C to $+175^\circ\text{C}$

Part Number	Maximum Recurrent Peak Reverse Voltage	Maximum DC Blocking Voltage
CSR012-065C1	650V	650V

Maximum Rating	Symbol	Conditions	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_C=25^\circ\text{C}$	650	V
Continuous forward current	I_F	$T_C=25^\circ\text{C}$	41	A
		$T_C=135^\circ\text{C}$	18	
		$T_C=155^\circ\text{C}$	12	
Non-repetitive forward sure current	I_{FSM}	$T_C=25^\circ\text{C}$, $t_p=10$ ms Half sine wave	95	A
		$T_C=125^\circ\text{C}$, $t_p=10$ ms Half sine wave	85	
Repetitive peak forward sure current	I_{FRM}	$T_C=25^\circ\text{C}$, $t_p=10$ ms Half sine wave, $D=0.1$	67	A
I^2t value	$\int i^2 dt$	$T_C=25^\circ\text{C}$, $t_p=10$ ms	45	A^2s
Power Dissipation	P_D	$T_C=25^\circ\text{C}$	125	W
		$T_C=125^\circ\text{C}$	41	



Package Dimensions



Symbol	mm		
	Min.	Typ.	Max.
A	4.24	4.44	4.64
A1	1.15	1.27	1.40
A2	2.30	2.48	2.70
b	0.70	0.80	0.90
b1	1.20	1.55	1.75
b2	1.20	1.45	1.70
c	0.40	0.50	0.60
D	14.70	15.37	16.00
D1	8.82	8.92	9.02
D2	12.63	12.73	12.83
E	9.96	10.16	10.36
E1	6.86	7.77	8.89
E3*	8.70 REF		
e	2.54 BSC		
e1	5.08 BSC		
H1	6.30	6.45	6.60
L	13.47	13.72	13.97
L1	3.60	3.80	4.00
ϕP	3.75	3.84	3.93
Q	2.60	2.80	3.00
Q1*	1.73 REF		
R*	1.82 REF		

NOTE :

1. These Dimension Do Not Include Mold protrusion

Electrical Characteristics, at $T_C=25^\circ\text{C}$, unless otherwise specified.

Static Characteristics	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
DC blocking voltage	V_{DC}	$I_R=100\ \mu\text{A}$, $T_J=25^\circ\text{C}$	650	-	-	V
Diode forward voltage	V_F	$I_F=12\text{A}$, $T_J=25^\circ\text{C}$	-	1.25	1.5	
		$I_F=12\text{A}$, $T_J=175^\circ\text{C}$	-	1.4	1.7	
Reverse current	I_R	$V_R=650\text{V}$, $T_J=25^\circ\text{C}$	-	4	60	μA
		$V_R=650\text{V}$, $T_J=175^\circ\text{C}$	-	240	-	

AC Characteristics

Static Characteristics	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Total capacitive charge	Q_C	$I_F=12\text{A}$, $di/dt=300\text{A}/\mu\text{s}$ $V_R=400\text{V}$, $T_J=25^\circ\text{C}$	-	33	-	nC
Total capacitance	C_j	$V_R=0.1\text{V}$, $f=1\text{ MHz}$ $T_J=25^\circ\text{C}$	-	847	-	pF
		$V_R=200\text{V}$, $f=1\text{ MHz}$ $T_J=25^\circ\text{C}$	-	76	-	
		$V_R=400\text{V}$, $f=1\text{ MHz}$ $T_J=25^\circ\text{C}$	-	58	-	
Capacitance stored energy	E_C	$V_R=400\text{V}$	-	6.4	-	μJ

Thermal Characteristics

Static Characteristics	Symbol	Values	Unit
		typ.	
Thermal resistance from junction to case	$R_{\theta JC}$	1.2	$^\circ\text{C}/\text{W}$

Typical Device Performance

Fig.1 Forward Characteristics

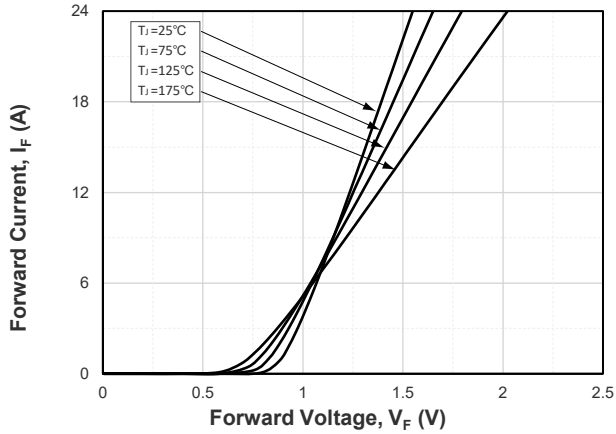


Fig.2 Reverse Characteristics

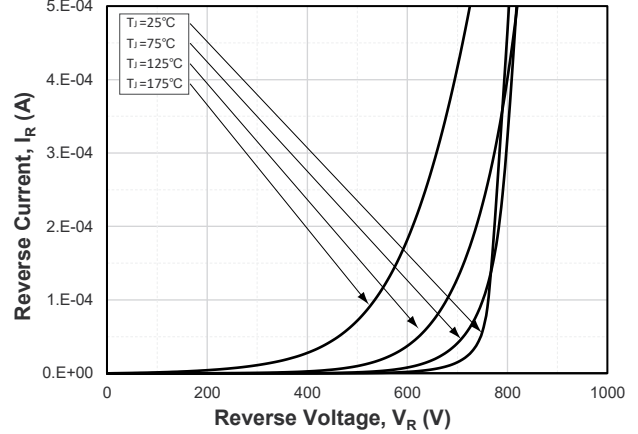


Fig.3 Junction Capacitance vs. Reverse Voltage

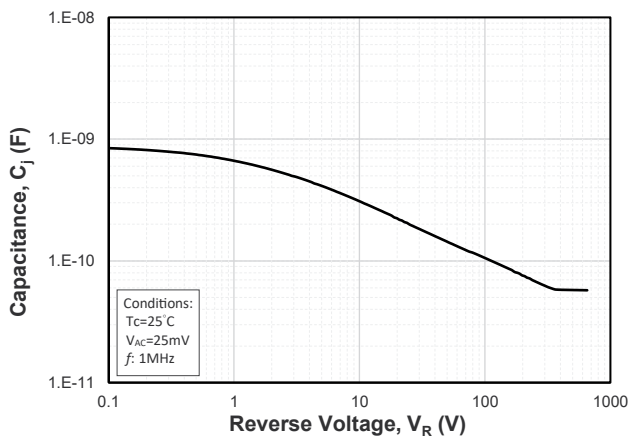


Fig.4 Capacitance Stored Energy

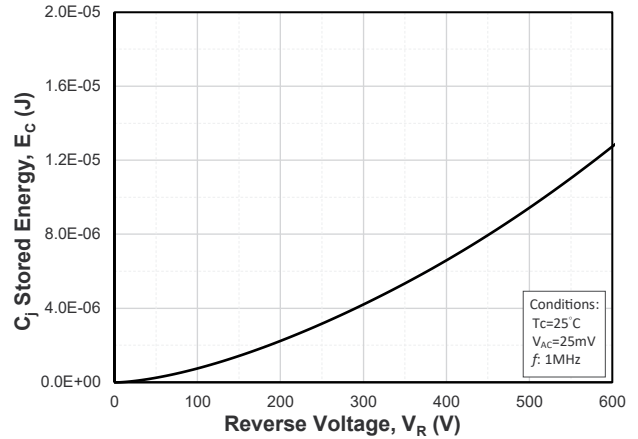


Fig.5 Recovery Charge vs. Reverse Voltage

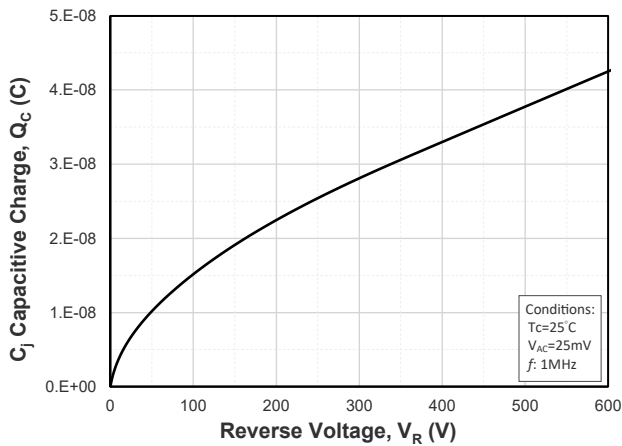
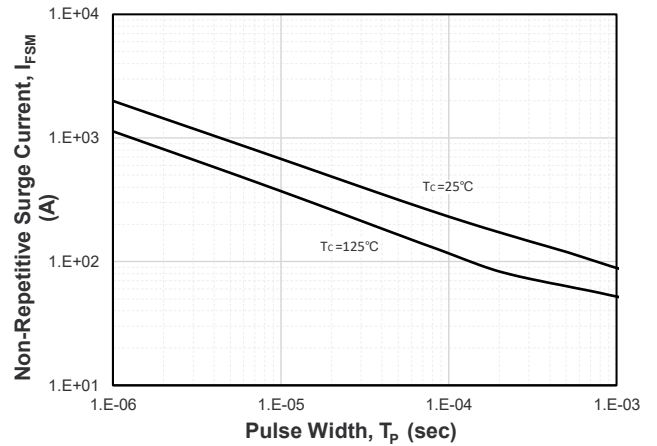


Fig.6 Non-Repetitive Peak Forward Surge Current (Pulse Mode)



Typical Device Performance

Fig.7 Maximum Forward Current Derating vs. Case Temperature

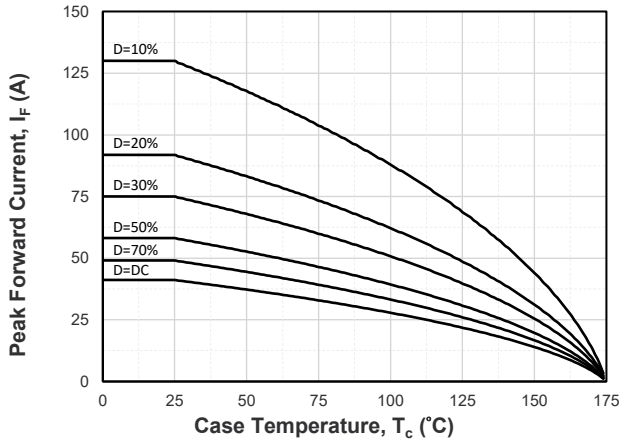


Fig.8 Maximum Power Dissipation Derating vs. Case Temperature

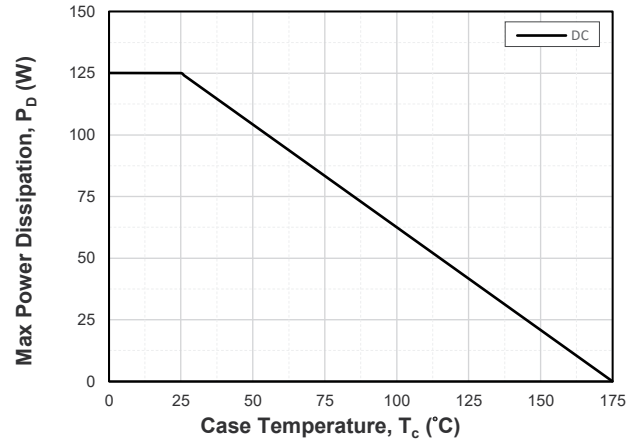
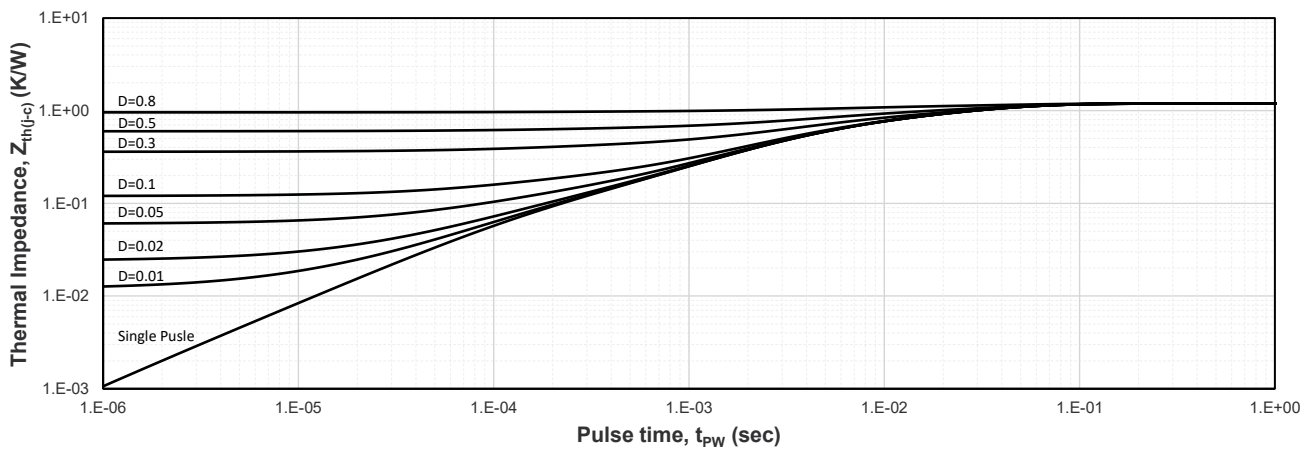


Fig.9 Transient Junction to Case Thermal Impedance



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